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Interfacing with ECLinPS



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APPLICATION NOTE

STANDARD ECL INTERFACE: DIFFERENTIAL DRIVER AND RECEIVER

A typical Emitter Coupled Logic (ECL) circuit interface may be defined as a differential driver device sending a paired set of commentary signals – True and Invert – over a pair of standard, controlled impedance lines to an ECL differential receiver device. A typical ECL output line driver consists of a bipolar transistor in an Emitter Follower configuration with the collector at V_{CC} power supply rail and the emitter pinned out. A standard, typical differential ECL receiver consists of a pair of bipolar transistors in a differential configuration with the True and Invert signals providing base drives to the two base inputs. Proper differential levels are specified as V_{pp} and V_{IHCMR} . When an input is interconnected as a differential signal, the DC Single Ended parameters of V_{IL} and V_{IH} do not apply. Terminations are required to preserve optimum signal integrity, as shown in Figure 1. The standard, controlled impedance lines assume a sufficient return current capability.

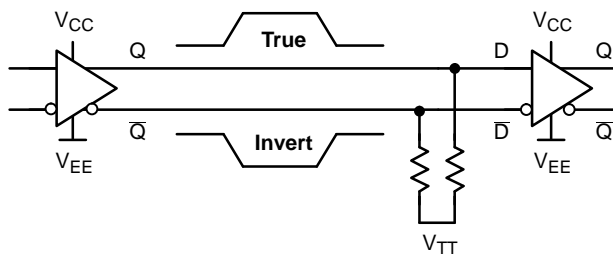


Figure 1. Standard Differential ECL Interconnect

SINGLE-ENDED INTERFACE

Signals may be imported as full differential lines or as a Single-Ended (SE) line interconnection. The SE interconnection may be seen as a special variation of the typical differential interface using only one driver source trace line. This single trace line drives a (Base) input pin of the receiver, as shown in Figure 2. Although a receiver may present only a single, dedicate SE input pin instead of a differential input pair of pins, such a receiver still would have a differential structure with the unavailable input controlled by internal circuitry.

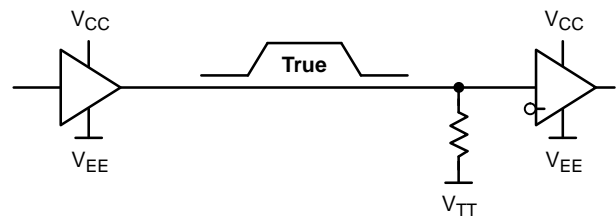


Figure 2. Standard Single-Ended ECL Interconnect

Single-ended receiver input levels are specified in data sheets DC CHARACTERISTICS block as V_{IH} and V_{IL} Parameters. Each temperature has a minimum and maximum limit pair to V_{IH} and V_{IL} parameters, thus defining the Single-Ended input swing, $V_{pp(SE)}$. The $V_{pp(SE)}$ ranges from 595 mV to 890 mV, depending on the temperature and family. The $V_{pp(SE)}$ limits constitute the receiver device's input single-ended sensitivity.

Both output lines of the typical differential output may drive two independent single-ended receivers separately (see Figure 3).

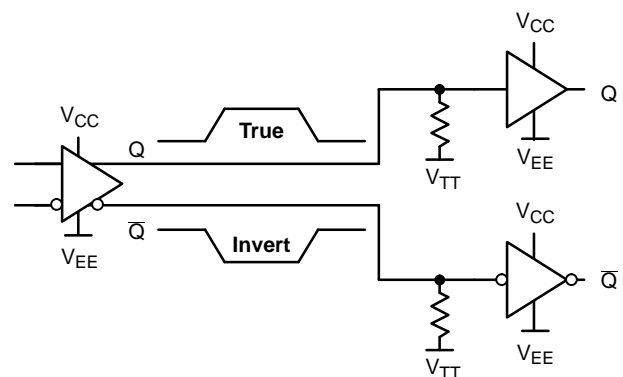


Figure 3. Differential Driver with Independent Standard Single-Ended Receivers

V_{BB} Reference

For a standard differential receiver with two input pins – D and \bar{D} – only one of two inputs is suitably selected to receive the signal while the non-driven input must be biased to a (DC) reference voltage, V_{BB} (see Figure 4).

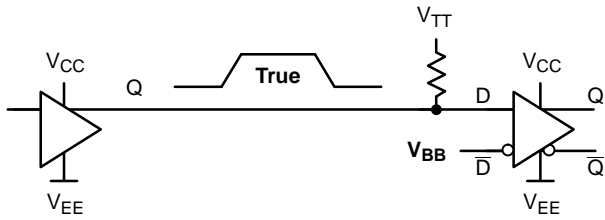


Figure 4. Standard SE Receivers with V_{BB}

The V_{BB} value is designed to be maintained midway (50%) between the HIGH and LOW levels of the received signal, that is, the crosspoint voltage of a differential signal pair, to preserve the duty cycle and signal integrity (see Figure 5).

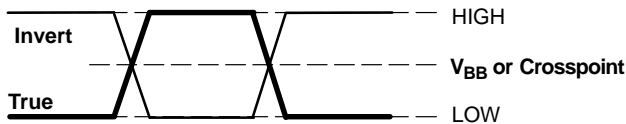


Figure 5. V_{BB} Crosspoint Voltage

If V_{BB} shifts, due to drift or noise, above the input signal 50% crosspoint, the device output signal will shift the duty cycle away from a pure 50% point to a decreased, narrowing pulse width (see Figure 6).

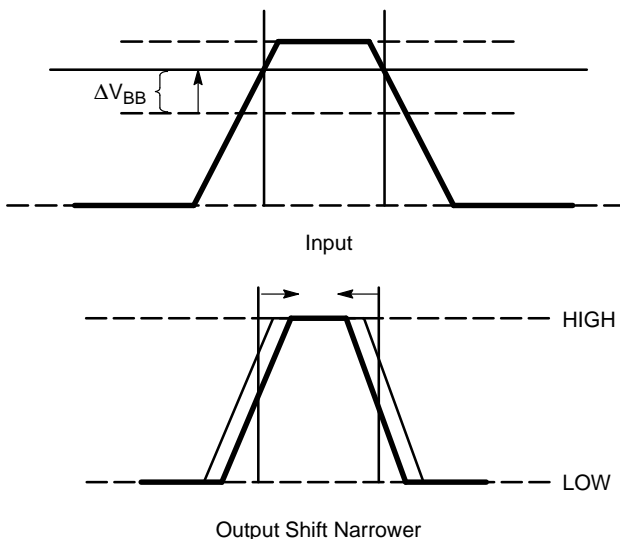


Figure 6.

If V_{BB} shifts below the input signal 50% crosspoint, the device output signal will shift the duty cycle away from a pure 50% point to an increased, widening pulse width (see Figure 7).

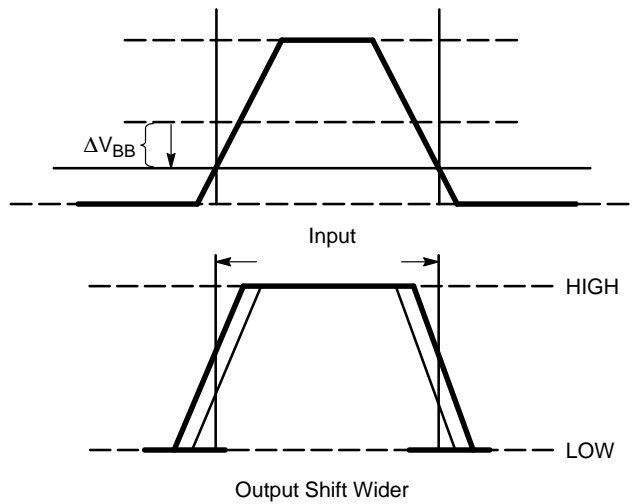


Figure 7.

Obviously, any error voltage present on the V_{BB} reference level injects jitter directly into the signal.

V_{BB}: Voltage Reference Sources

A V_{BB} reference voltage output source pin may be available on the receiver device. When present, V_{BB} is an internally generated voltage supply and available only to that device's inputs. Current demand on the V_{BB} pin should be limited to 0.5 mA. Bypass (0.01 μF) V_{BB} to the quietest plane, usually V_{CC}, since noise on V_{BB} will inject jitter and corrupt duty cycle. The V_{BB} voltage is derived from referencing the V_{CC} supply and will track changes in V_{CC} 100% or 1:1. If V_{CC} shifts 1 mV, then V_{BB} also changes 1 mV. Changes in V_{EE} also affect the V_{BB} voltage and will track at the rate of 0 to 20%, typically 5%. If V_{EE} shifts 100 mV, then V_{BB} follows with a 0 mV to 20 mV shift of the same polarity, typically 5 mV.

A V_{BB} reference voltage may be generated off-device and supplied to the input pins. Ripple content must be kept as low as possible on V_{CC} since it transfers to the signal as jitter and phase error. A V_{BB} voltage reference level may be supplied from a V_{BB} generator, as shown in Figure 8. Any of the “16” type buffers are recommended to produce a high current gain V_{BB} buffer. For example, the E416, EL16, LVEL16, EP16, LVEP16, EL17, LVEL17, etc. type devices have a V_{BB} pin available. A 1 KΩ resistor may be needed the feedback path to stabilize higher gain buffers.

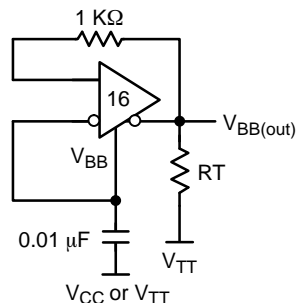


Figure 8. V_{BB} Voltage Reference Generator

Depending on system requirements, V_{BB} may be generated by a dedicated supply, a “16” type buffer, or by using a bypassed resistor voltage divider.

Dedicated Single-Ended Input Structure

A device may have a dedicated single-ended input, having only one of the internal differential base inputs pinned out of the package, available to be driven by a signal. Internal circuitry connects a V_{BB} voltage reference to the other internal, non-driven input base node of the differential buffer gate, as shown in Figure 2. This internal, fixed reference voltage, V_{BB} , is maintained at the midpoint between V_{IL} and V_{IH} for dedicated single-ended inputs. The internal V_{BB} is derived from referencing the V_{CC} supply and tracks changes 1:1 in this supply. Noise and drift in V_{CC} will inject jitter and phase noise directly into the signal.

DIFFERENTIAL INTERFACE

A standard differential interconnect driver signal will be received as signal swing. Historically, standard ECL driver signal swing may range from 750 mV to 1040 mV depending on the family, although 800 mV is typical. Newer devices may offer RSECL (Reduced Swing ECL) or Variable Output Swing (NBSG16VS). Receiver sensitivity is specified by data sheets as the input swing voltage peak-to-peak (V_{pp}). Proper output operation is displayed as the typical amplitude through the entire range of input swing, from minimum to maximum as shown in Figure 9: V_{pp} – Input Swing Voltage Peak-to-Peak. Input swings greater than specification limit maximum may cause degraded frequency performance and increased t_{pd} input. Input swings less than specification minimum will cause diminished output amplitude due to the device voltage gain and low enough input amplitude will result in a loss of output signal. All waveforms are measured with single ended probes with reference to ground (not as a differential probe value). Operation in the small signal level range less than V_{pp} minimum display a characteristic gain and may obviously be operated as a limited linear amplifier this input swing range.

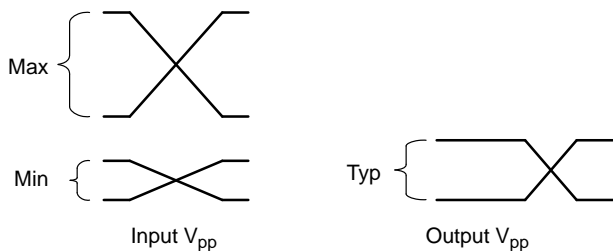


Figure 9. V_{pp} – Input Swing Voltage Peak-to-Peak

Noise common to both differential lines and within the input operating range will be rejected and ignored by the receiver. The transfer threshold point is determined by the crosspoint of the differential signal. A voltage shift in input operating range of the transfer point has no voltage or timing effect on the signal, therefore, preserving integrity. A receiver’s tolerance of common mode interference is illustrated in Figure 10.

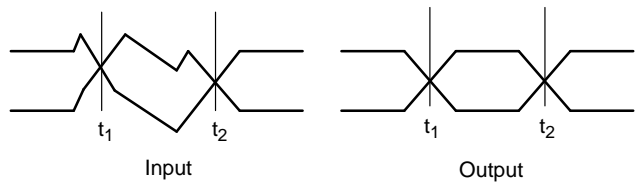


Figure 10. Differential Input High Noise Immunity

V_{IHCMR}

Each input signal to a differential pair receiver will display a V_{in} HIGH voltage (V_{IH}) level and a V_{in} LOW voltage V_{IL} . Proper operation is achieved when the V_{in} HIGH voltage (V_{IH}) level falls within spec limits, V_{IHCMR} (Voltage Input High Common Mode Range) minimum to maximum as represented in Figure 11.

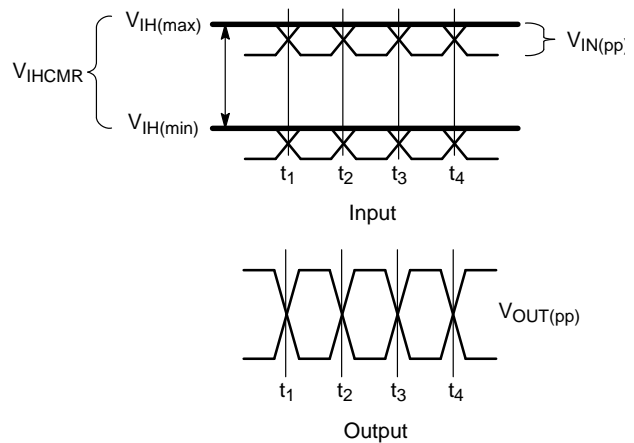


Figure 11. V_{IH} Common Mode Range, V_{IHCMR}

Considerations for Single-Ended and Differential Interconnects

Several advantages and disadvantages are listed below.

Single-Ended (SE) Interconnects

Advantages may include:

- Decreased board real estate routing.
- Reduced system power demand.

Disadvantages may include:

- Higher jitter, phase error, and duty cycle skew.
- High noise sensitivity.
- Critically narrow interface windows.
- Poor receiver sensitivity.
- Higher EMI emission.

Differential Interconnects

Advantages may include:

- High common mode noise rejection (low noise sensitivity).

- Wide signal interface windows.
- High receiver sensitivity.
- Low EMI emission.

Disadvantages may include:

- Increased board routing real estate.
- Increased system power demand.

ECL 10 and 100 Performance Standards

There currently exist two basic legacy standards for high performance ECL logic devices.

10 Series (compatible with 10H)

100 Series (compatible with 100K)

Both standards display similar highly compatible output amplitude swings of about 800 mV_{pp} over a wide range of operating conditions and loads. This is due to drivers enjoying a remaining internal output impedance ranging from 6 to 8 Ω in both HIGH and LOW level state levels (see Figure 12).

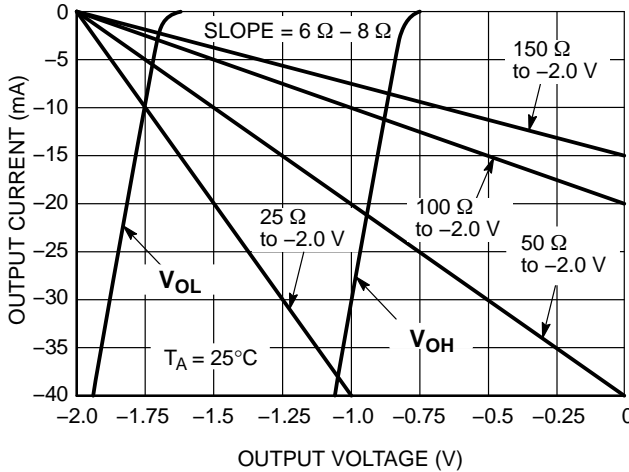


Figure 12. Outputs vs. Load Drive Characteristics

For loads of 35 ohms or less, outputs may need to be “ganged” (wire “ANDed”), or specialized 25-Ω driver circuits deployed. These specialized drivers ensure reduced power dissipation and improve long term reliability. Both standards display similar rise/fall times, propagation delays, and toggle frequencies.

Differential Interface Between 10 and 100 Standards

When interfacing differentially, the two basic standards are completely, directly compatible over all operational conditions. This results from receivers of both standards exhibiting wide V_{IH} Common Mode Range and fine minimum input sensitivity, V_{pp}. Output temperature variations associated with 10 Series devices are well within these receiver input characteristic limitations.

Single-Ended (SE) Interface Between 10 and 100 Standards

Single-Ended (SE) line signal interconnects require analysis of both the driver output levels, V_{OH} and V_{OL}, across temperature and the receiver input voltage level limits, V_{IH} and V_{IL}, to determine complete interface compatibility. Although 100 Series standard devices incorporate a temperature compensation network in the output driver, some variation may still be observed. Variation of the driver output levels, V_{OH} and V_{OL}, across temperature is typically present in 10 Series devices.

Device series voltage transfer curves characterize the input and output behavior function across temperature. This is shown in Figures 13 through 16 for 10E, 100E, 10K, and 10KH Series. Changes in technology refinements to the 10K Series led to the 10KH Series with better performance in V_{IH} and V_{OL} as V_{in} approached V_{CC}. The 10E Series is similar to the 10KH Series. Temperature compensation allowed the development of the 100 Series.

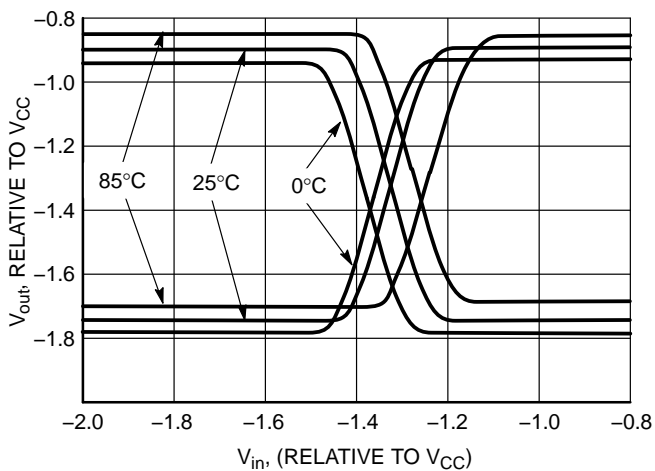


Figure 13. 10E Series Vin vs. Vout Transfer Curves

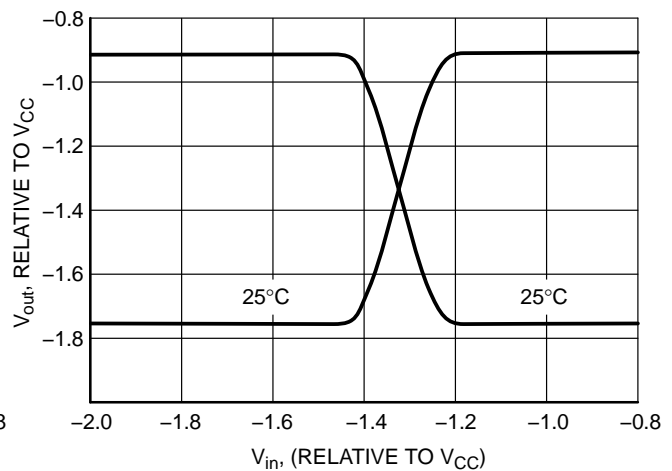


Figure 14. 100E Series Vin vs. Vout Transfer Curves

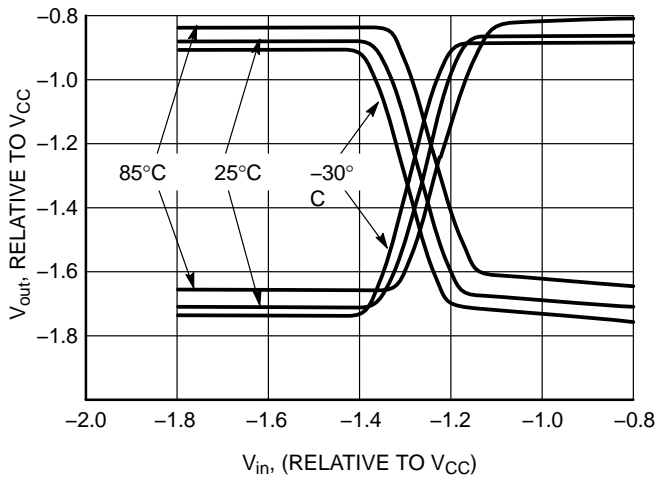


Figure 15. 10K Series Vin vs. Vout Transfer Curves

The difference in the DC behavior of the inputs and outputs of the two different standards necessitates caution when mixing the two technologies in single-ended designs. Output levels become critical to the receiver when the V_{OH} minimum, V_{OHA} , drives into the receiver as the V_{IH} minimum. Levels are also critical when the driver V_{OL} maximum, V_{OLA} , drives into the receiver as the V_{IL} maximum.

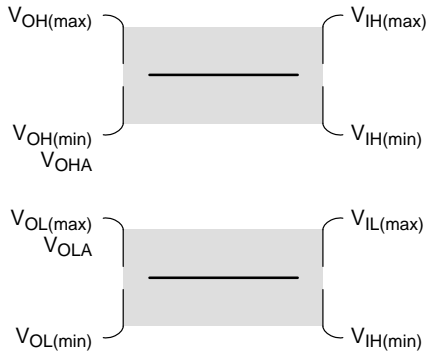


Figure 17. Single-Ended Noise Margin

Noise margin quantifies the susceptibility of a driver and receiver interface to any non-signal voltage levels and therefore risking false switching. Two measurements – NOISE MARGIN HIGH and NOISE MARGIN LOW – describe the false switching risk across temperature as follows:

$$\text{NOISE MARGIN}_{(\text{HIGH})} = V_{OH(\text{min})} - V_{IH(\text{min})}$$

$$\text{NOISE MARGIN}_{(\text{LOW})} = V_{OL(\text{max})} - V_{IL(\text{max})}$$

An MC10EP16DT, operating in LVPECL mode with 3.3 V on V_{CC} and 0.0 V on V_{EE} , interfaced to an MC10EP16DT receiver, single-ended, has a noise margin at the specification ambient temperature shown in Table 1. Notice the safety margin levels are positive for NOISE MARGIN HIGH indicating the driver exceeds the receiver’s requirement for a minimum and the delta is positive. For a NOISE MARGIN

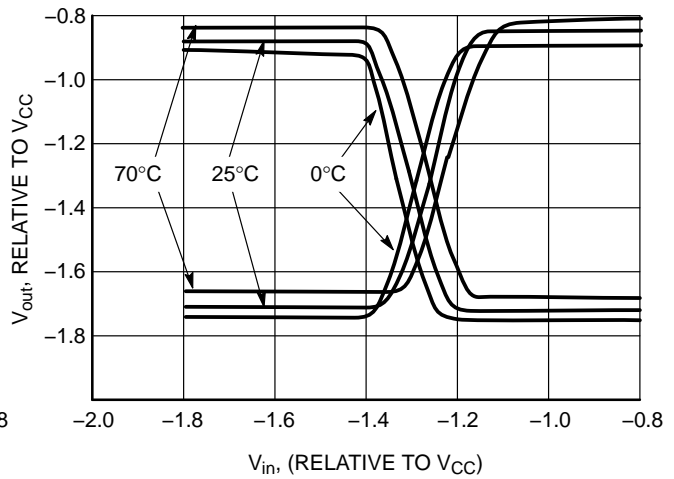


Figure 16. 10KH Series Vin vs. Vout Transfer Curves

LOW, the driver must be below the receiver’s maximum and the delta is negative.

Table 1. Noise Margins: MC10EP16DT Interfaced to an MC10EP16DT Receiver

10 to 10 Noise Margin HIGH	Temp.	$V_{OH(\text{min})} - V_{IH(\text{min})}$	Delta (mV)
	-40°C	2165 – 2090	75
	25°C	2230 – 2155	75
	85°C	2290 – 2215	75
10 to 10 Noise Margin LOW	Temp.	$V_{OL(\text{max})} - V_{IL(\text{max})}$	Delta (mV)
	-40 °C	1615 – 1690	-40
	25°C	1680 – 1755	-75
	85°C	1740 – 1810	-70

When a 10 Series device drives a 100 Series device single-ended, the noise margins become a risk factor requiring careful evaluation as indicated in Table 2.

Table 2. Noise Margins: MC10EP16DT Interfaced to an MC100EP16DT Receiver

10 to 100 Noise Margin HIGH	Temp.	$V_{OH(\text{min})} - V_{IH(\text{min})}$	Delta (mV)
	-40°C	2165 – 2075	90
	25°C	2230 – 2075	155
	85°C	2290 – 2075	215
10 to 100 Noise Margin LOW	Temp.	$V_{OL(\text{max})} - V_{IL(\text{max})}$	Delta (mV)
	-40 °C	1615 – 1675	-60
	25°C	1680 – 1675	5
	85°C	1740 – 1675	65

When a 100 Series device drives a 10 Series device, single-ended, the noise margins are very robust and immunity is optimized (See Table 3).

Table 3. Noise Margins: MC100EP16DT Interfaced to an MC10EP16DT Receiver

100 to 10 Noise Margin HIGH	Temp.	V _{OH(min)} – V _{IH(min)}	Delta (mV)
	–40°C	2405 – 2090	315
	25°C	2405 – 2155	250
	85°C	2405 – 2215	190
100 to 10 Noise Margin LOW	Temp.	V _{OL(max)} – V _{IL(max)}	Delta (mV)
	–40°C	1605 – 1690	–85
	25°C	1605 – 1755	–150
	85°C	1605 – 1810	–205

Edge Rates (dV/dT)

As a driver rising edge approaches the transfer voltage point of the receiver input, the receiver diminishes in voltage according to the small signal gain of the device. When the input voltage level passes through the transfer crosspoint, the output will “switch” states in an analog or operational amplifier mode. Non-signal voltage fluctuations and noise will be amplified. These phenomena will determine the suitable edge rate limitation. As the edge becomes slower, ambient noise present on the input pin will typically constrain practical usability. Typically, this may be from 5 ns to 35 ns and further precaution, such as shielding, will extend the operating edge times.

For signal edges slower than 20 ns, a Schmitt trigger circuit may be considered to reliably sharpen the edge rates. In theory, ECL logic may operate from sub-hertz (< 1.0 Hz) frequencies, but real circuit conditions will constrain practical limits.

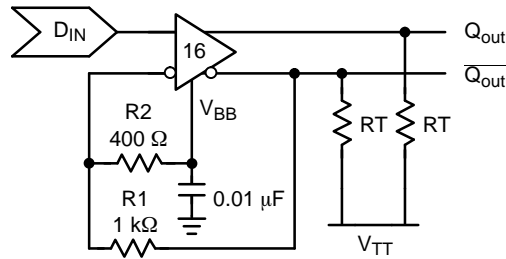



Figure 18. Schmitt Trigger with 228 mV Hysteresis

Schmitt conditioning may be determined by the resistor values. An R1 resistor of 1 kΩ provides inverted output feedback resistor (R_{fb}) from Q_{out} to the threshold voltage point, \bar{D} . A 400 Ω bias resistor, R2, to V_{BB} sets the voltage offset as a fraction of the output voltage from V_{BB}. With an 800 mV V_{out} swing, V_{BB} will be the midpoint between V_{OH} and V_{OL}, or 400 mV from a state level. The two resistors form a voltage divider from either state level to V_{BB}. About 28% of the LOW or HIGH state level is developed at the voltage divider node and ported to \bar{D} . This will be the offset a signal must exceed to force the buffer to switch states.

$$\begin{aligned} \text{For } t_r \text{ Voffset} &= \frac{R2}{R1 + R2} * (V_{OL} - V_{BB}) \\ &= \frac{400}{1400} * 400 \\ &= 114\text{mV} \end{aligned}$$

$$\begin{aligned} \text{For } t_f \text{ Voffset} &= \frac{R2}{R1 + R2} * (V_{OH} - V_{BB}) \\ &= \frac{400}{1400} * 400 \\ &= 114\text{mV} \end{aligned}$$

This creates a total of 228 mV of hysteresis conditioning. The effect of the hysteresis delay in a signal must be considered in the timing analysis.

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